TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π -MOSVI)

TPC8004

Lithium Ion Battery Applications Portable Equipment Applications Notebook PC Applications

- Small footprint due to small and thin package
- Low drain-source ON resistance $: R_{DS} (ON) = 37 \text{ m}\Omega (typ.)$
- High forward transfer admittance : $|Y_{fs}| = 6 S (typ.)$
- Low leakage current $: I_{DSS} = 10 \ \mu A \ (max) \ (V_{DS} = 30 \ V)$
- Enhancement-mode : $V_{th} = 0.8 \sim 2.0 V (V_{DS} = 10 V, I_D = 1 mA)$

Maximum Ratings (Ta = 25°C)

Characte	ristics	Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	30	V	
Drain-gate voltage (F	R _{GS} = 20 kΩ)	V _{DGR}	30	V	
Gate-source voltage		V _{GSS}	±20	V	
Drain current	DC (Note 1)	۱ _D	5	A	
Diameditent	Pulse (Note 1)	I _{DP}	20		
Drain power dissipati	on (t = 10 s) (Note 2a)	PD	2.4	W	
Drain power dissipati	on (t = 10 s) (Note 2b)	PD	1.0	W	
Single pulse avalanc	he energy (Note 3)	E _{AS}	32.5	mJ	
Avalanche current		I _{AR}	5	А	
Repetitive avalanche (energy Note 2a) (Note 4)	E _{AR}	0.24	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature	range	T _{stg}	−55 to 150	°C	



This transistor is an electrostatic sensitive device. Please handle with caution.





Weight: 0.080 g (typ.)

Circuit Configuration



Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R _{th (ch-a)}	52.1	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R _{th (ch-a)}	125	°C/W

Marking (Note 5)



Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a)







Note 3: V_{DD} = 24 V, T_{ch} = 25°C (initial), L = 1.0 mH, R_G = 25 Ω , I_{AR} = 5 A

Note 4: Reptitve rating; pulse width limited by maximum channel temperature

Note 5: ● on lower left of the marking indicates Pin 1.

% shows lot number. (year of manufacture: last decimal digit of the year of manufacture, month of manufacture: January to December are denoted by letters A to L respectively.)

Electrical Characteristics (Ta = 25°C)

Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μA
Drain cut-off cur	rent	I _{DSS}	V_{DS} = 30 V , V_{GS} = 0 V	_	—	10	μA
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	30	_		V
Gate threshold v	oltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	0.8	—	2.0	V
Drain-source ON resistance		R _{DS (ON)}	V _{GS} = 4 V, I _D = 2.5 A	_	58	80	mΩ
			V _{GS} = 10 V, I _D = 2.5 A		37	50	
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 2.5 A	3	6	_	S
Input capacitance	e	C _{iss}			475	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	85	_	pF
Output capacitance		C _{oss}		_	270	_	
Switching time	Rise time	tr	$V_{GS} \stackrel{10 \text{ V}}{}_{0 \text{ V}} \stackrel{I_{D} = 2.5 \text{ A}}{}_{0 \text{ V}} \stackrel{V_{OUT}}{}_{RL} = \\ \stackrel{\bullet}{}_{6 \Omega} \stackrel{\bullet}{}_{777} \stackrel{V_{DD}}{}_{777} = 15 \text{ V}$ Duty $\leq 1\%$, t _w = 10 μ s	_	10	_	ns
	Turn-on time	t _{on}		_	16	_	
	Fall time	t _f		_	13	_	
	Turn-off time	t _{off}		_	70	_	
Total gate charge (Gate-source plus gate-drain)		Qg	V _{DD} ≈ 24 V, V _{GS} = 10 V, I _D = 5 A	_	16	_	nC
Gate-source charge		Q _{gs}		—	11	—	
Gate-drain ("miller") charge		Q _{gd}		-	5	-	

Source–Drain Ratings and Characteristics (Ta = 25°C)

Charact	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	—			20	A
Forward voltage	(diode)	V _{DSF}	I _{DR} = 5 A, V _{GS} = 0 V	_	_	-1.2	V







